H242-Z10

Edge Server - AMD UP 2U 4 Nodes







Features

- Supports 5G network infrastructure
- 2U 4 nodes rear access server system for Edge Computing
- Single AMD EPYC[™] 7002 series processor family
- 4 x LGA 4094 sockets
- 8-Channel RDIMM/LRDIMM DDR4, 32 x DIMMs
- 8 x 1Gb/s LAN ports (Intel® I350-AM2)
- 4 x 2.5" NVMe hot-swappable SSD bavs
- 8 x M.2 with PCIe Gen3 x4 interface
- 8 x Low profile PCle x16 expansion slots
- 4 x OCP 2.0 Gen3 x16 mezzanine slots
- Aspeed® AST2500 remote management controller
- 2+0 1200W 80 PLUS Platinum power supply

AMD EPYC™ 7002 Series Processor (Rome)

The next generation of AMD EPYC has arrived, providing incredible compute, IO and bandwidth capability – designed to meet the huge demand for more compute in big data analytics, HPC and cloud computing.

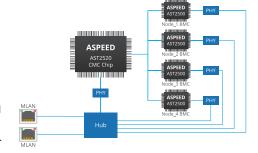
- Suilt on 7nm advanced process technology, allowing for denser compute capabilities with lower power consumption
- Up to 64 core per CPU, built using Zen 2 high performance cores and AMD's innovative chiplet architecture
- Supporting PCIe Gen 4.0 with a bandwidth of up to 64GB/s, twice of PCIe Gen 3.0
- Embedded security protection to help defend your CPU, applications, and data

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Optional CMC / Ring Topology Module

GIGABYTE's H242-Series servers include support for an optional CMC / Ring Topology Module, featuring an Aspeed CMC (Central Management Controller), LAN hub and dual MLAN ports for multi-node management (including iKVM support) by connecting internally to Aspeed BMCs integrated on each node. This results only in one MLAN connection required to perform management of all four nodes, resulting in less ToR (Top of Rack) cabling and switch connections.

In addition, the LAN hub and dual MLAN ports support the ability to create a "ring" connection for management of all servers in the rack - only two ToR (Top of Rack) switch connections are needed to create the ring system, and the ring will not be broken even if one server in the chain is shut down, reducing cabling and switch port usage for greater cost savings and management efficiency.



GIGABYTE Management Console (AMI MegaRAC SP-X)

This GIGABYTE server product utilizes a AMI MegaRAC SP-X platform for BMC server management, with a feature rich and easy to use browser-based graphical user interface. Notable features include:

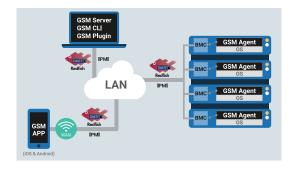
- RESTful API support (including the latest DMTF standards of Redfish) allows the administrator to integrate with 3rd party applications for server management
- HTML5-based iKVM remote management client included as a standard feature, no additional add-on license required to purchase
- Detailed FRU information from SMBIOS
- Pre-event automatic video recording feature from 10 to 30 seconds
- . SAS / RAID controller monitoring feature

GIGABYTE Server Management (GSM)

GIGABYTE Server Management (GSM) is GIGABYTE's proprietary multiple server remote management software platform, available as a free download from each GIGABYTE server product page. GSM is compatible with either IPMI or Redfish (RESTful API) connection interfaces, and comprises the following sub-programs:

• GSM Server • GSM CLI • GSM Agent • GSM Mobile • GSM Plugin





Specification

2U 4 Nodes - Rear access Power Supply 2+0 1200W 80 PLUS Platinum power supply Dimensions (WxHxD) 440 x 87.5 x 475 mm AC Input: - 100-240V~/ 12-7A, 50-60Hz Motherboard MZ12-HD0 DC Input: - 240Vdc/ 6A CPU AMD EPYC™ 7002 series processor family DC Output: Single processors, 7nm technology - Max 1000W/ 100-240V~ Up to 64-core, 128 threads per processor +12V/80.5A TDP up to 225W, cTDP up to 240W +12Vsb/3A Conditional support 280W - Max 1200W/ 200-240V~ or 240Vdc input +12V/97A Compatible with AMD EPYC™ 7001 series processor family +12Vsb/3A Socket Per node: 1 x LGA 4094 Aspeed® AST2500 management controller System Total: 4 x LGA 4094 Management GIGABYTE Management Console (AMI MegaRAC SP-X) Socket SP3 Dashboard Chipset System on Chip JAVA Based Serial Over LAN HTML5 KVM Memory Per node: 8 x DIMM slots Sensor Monitor (Voltage, RPM, Temperature, CPU Status ...etc.) Total: 32 x DIMM slots Sensor Reading History Data DDR4 memory supported only FRU Information 8-Channel memory architecture SEL Log in Linear Storage / Circular Storage Policy RDIMM modules up to 64GB supported Hardware Inventory LRDIMM modules up to 128GB supported Fan Profile Memory speed: Up to 3200 MHz System Firewall Power Consumption LAN Per node: 2 x 1GbE LAN ports (Intel® I350-AM2) Power Control 1 x Dedicated management port LDAP / AD / RADIUS Support Total: 8 x 1GbE LAN ports (Intel® I350-AM2) Backup & Restore Configuration 4 x Dedicated management ports Remote BIOS/BMC/CPLD Update **Event Log Filter** Video Integrated in Aspeed® AST2500 User Management 2D Video Graphic Adapter with PCIe bus interface Media Redirection Settings 1920x1200@60Hz 32bpp, DDR4 SDRAM PAM Order Settings SSL Settings Storage Per node: 1 x 2.5" NVMe hot-swappable SSD bay SMTP Settings Total: 4 x 2.5" NVMe hot-swappable SSD bays All storage bays are compatible with SATA devices Windows Server 2016 (X2APIC/256T not supported) os Compatibility Windows Server 2019 Expansion Red Hat Enterprise Linux 7.6 (x64) or later Slots 1 x Half-length low-profile slot with PCIe x16 (Gen4 x16) Red Hat Enterprise Linux 8.0 (x64) or later 1 x Half-length low-profile slot with PCle x16 (Gen3 x16) SUSE Linux Enterprise Server 12 SP4 (x64) or later 1 x OCP mezzanine slot with PCIe Gen3 x16 bandwidth SUSE Linux Enterprise Server 15 SP1 (x64) or later 2 x M.2 slots Ubuntu 16.04.6 LTS (x64) or later Ubuntu 18.04.3 LTS (x64) or later VMware ESXi 6.5 EP15 or later 4 x Half-length low-profile slot with PCle x16 (Gen4 x16) VMware ESXi 6.7 Update3 or later 4 x Half-length low-profile slot with PCle x16 (Gen3 x16) Citrix Hypervisor 8.1.0 4 x OCP 2.0 mezzanine slots with PCle Gen3 x16 bandwidth 8 x M.2 slots Net Weight: 17.2 kg / Gross Weight: 28.9 kg Weight - M-key, PCIe Gen3 x4 - Supports NGFF-2242/2260/2280/22110 cards 3 x 80x80x38mm (16,300rpm), 1 x 40x40x28mm (25,000rpm) System Fans - CPU TDP is limited to 155W if using M.2 device Operating Operating temperature: 10°C to 35°C Internal I/O Per node: Operating humidity: 8%-80% (non-condensing) 2 x M.2 slots, 1 x USB 3.0 header, 1 x TPM header, Non-operating temperature: -40°C to 60°C 1 x OCP 2.0 mezzanine slots, 1 x Front panel header, Non-operating humidity: 20%-95% (non-condensing) 1 x Back plane board header, 1 x IPMB connector, Ambient temperature limited to 30°C if using 280W CPU 1 x Clear CMOS jumper, 1 x BIOS recovery jumper **Packaging** 857 x 670 x 280 mm Front I/O Per node: 1 x Power button with LED, 1 x ID button with LED, **Dimensions** 1 x Status LED, 1 x Reset button Total: 4 x Power button with LED, 4 x ID button with LED, **Packaging** 1 x H242-Z10, 4 x CPU heatsinks,1 x Rail Kit 4 x Status LED, 4 x Reset button Content Rear I/O Per node: 2 x USB 3.0, 1 x VGA, 2 x RJ45, 1 x MLAN, 1 x ID LED Barebone package: 6NH242Z10MR-00 **Part Numbers** Total: 8 x USB 3.0, 4 x VGA, 8 x RJ45, 4 x MLAN, 4 x ID LEDs - Motherboard: 9MZ12HD0NR-00 - Back plane board: 9CBPH043NR-00 Backplane I/O 4 x ports Speed and bandwidth: - Rail kit: 25HB2-AA6107-K0R - CPU heatsink: 25ST1-44320J-A0R SATA 6Gb/s or SAS 12Gb/s or PCle Gen3 x4 per port - Back plane board: 9CBPH043NR-00 **TPM** 1 x TPM header with SPI interface - Fan module: 25ST2-44282D-D0R/ 25ST2-88382E-D0R Optional TPM2.0 kit: CTM010 - Power Supply: 25EP0-212007-F3S











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